IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants

:Akihiko ENDO et al.

Group Art Unit: 2812

Appl. No.

: 10/569,942

Examiner: Seahvosh J NIKMANESH

Filed

: February 28, 2006

Confirmation No.: 1077

For

: METHOD FOR MANUFACTURING BONDED WAFER

AMENDMENT UNDER 37 C.F.R. § 1.111

Commissioner for Patents
U.S. Patent and Trademark Office
Customer Service Window, Mail Stop <u>AMENDMENT</u>
Randolph Building
401 Dulany Street
Alexandria, VA 22314

Sir:

This paper is responsive to the Office Action mailed August 7, 2008. Applicants respectfully request reconsideration and withdrawal of each of the rejections of the outstanding Office Action, and request allowance of all the claims pending herein. Inasmuch as the three-month shortened statutory period is set in the Office Action to expire on November 7, 2008, this response is being filed in a timely manner and no fee for extension of time is deemed necessary. Should any extension of time fees or other fees be required to maintain pendency of the application, however, authorization is hereby provided to charge any fees to Deposit Account No. 19-0089.

Amendments to the Drawings are discussed on page 2 and are attached hereto.

Amendments to the Claims are shown in the Listing of Claims, which begins on page 3 of this paper.

Remarks begin on page 5 of this paper.